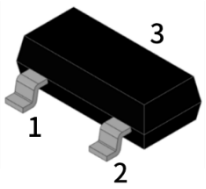
MMBD914LST1

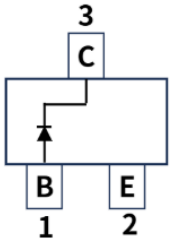
SWITCHING DIODE

1. FEATURES

- The material of product compliance with RoHS requirements and Halogen Free.
- High-Speed Switching Diode.

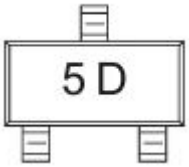


SOT23 (TO-236)



2. Mechanical Data

- SOT-23 Small Outline Plastic Package.
- Tin plated leads, solderable per J-STD-002 and JESD22-B102.
- Marking: 5D



3. ORDERING INFORMATION

Device	Min Pack	Inner Box	Outer Carton	Reel
MMBD914LST1	3000	45000	180000	7 inch

4. MAXIMUM RATINGS (Ta = 25ºC)

Parameter	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	VRM	100	V
Peak Repetitive Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	VRRM VRWM VR	100	V
Average Rectified Output Current	I0	0.3	A
Non-Repetitive Peak orward Surge Current .t=8.3mS	IFSM	2	A

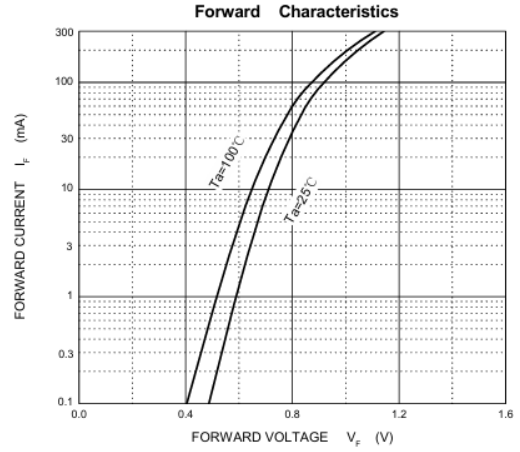
5. THERMAL CHARACTERISTICS

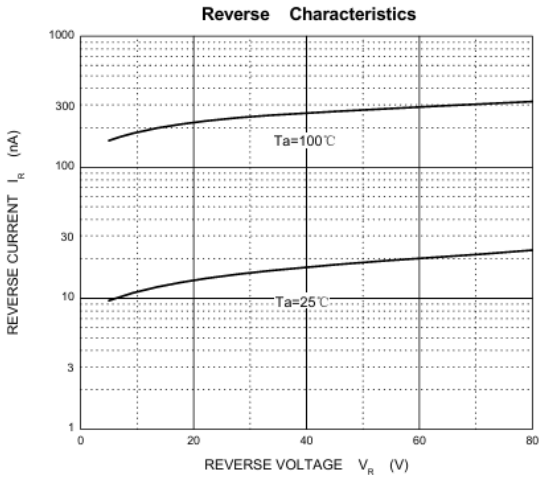
Parameter	Symbol	Limit	Unit
Total Device Dissipation TA = 25ºC	PD	350	mW
Thermal Resistance J to A	RθJA	357	°C/W
Junction and Storage temperature	TJ, TSTG	−55~+150	°C

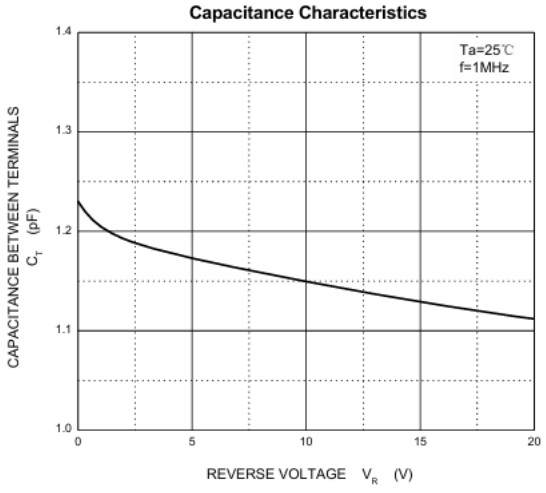
6.MOSFET ELECTRICAL CHARACTERISTICS (Ta= 25ºC unless otherwise specified)

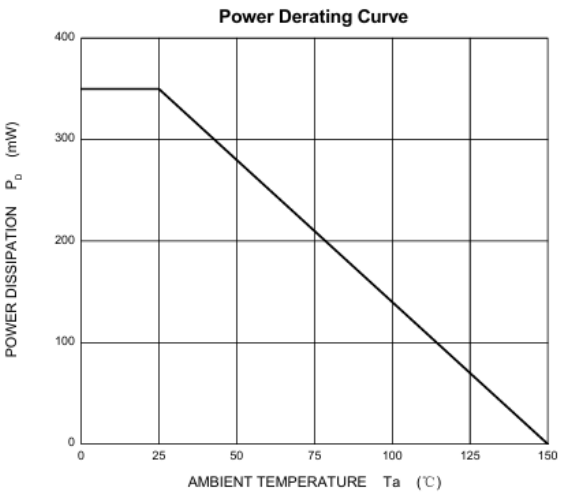
Parameter	Symbol	Condition	Min	TYP	Max	Unit
Reverse Breakdown Voltage	VBR	IR = 100 μA	100			V
Forward Voltage	VF1	IF=1mA			715	mV
	VF2	IF=10 mA			855	mV
	VF3	IF=50 mA			1000	mV
	VF4	IF=150 mA			1250	mV
Reverse Current	IR1	VR=75V			1	μA
	IR2	VR=20V			25	nA
Diode Capacitance	CD	VR=0 ,f=1MHz			2	pF
Reverse Recovery Time	trr	IF=IR=10mA,Irr=0.1*IR			4	ns

7.ELECTRICAL CHARACTERISTICS CURVES

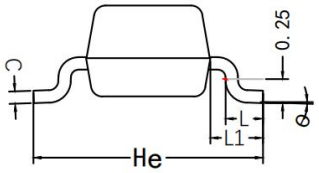


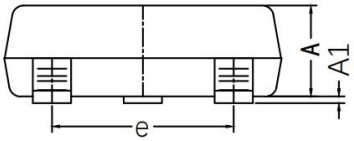


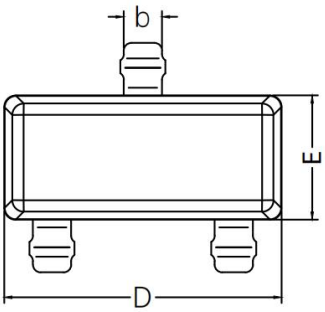




6. OUTLINE AND DIMENSIONS

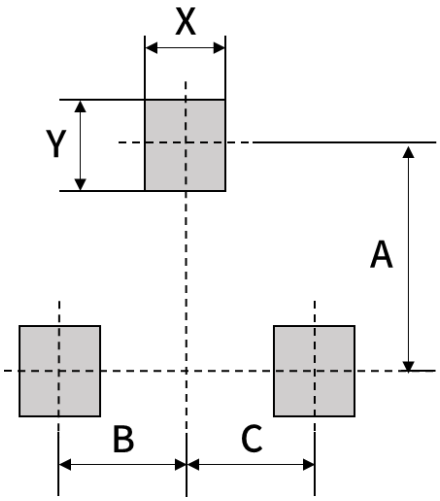






DIM	MIN	NOR	MAX
A	0.85	0.95	1.05
A1	0.01	0.06	0.10
b	0.36	0.44	0.52
c	0.09	0.13	0.18
D	2.80	2.90	3.10
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.40	0.50
L1	0.35	0.50	0.65
He	2.10	2.35	2.50
θ	0°	-	10°
All Dimensions in mm			

7. SUGGESTED PAD LAYOUT



SOT23		
DIM	mm	inch
A	2.00	0.079
B	0.95	0.037
C	0.95	0.037
X	0.80	0.031
Y	0.90	0.035

8. DISCLAIMER

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